



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	01/13/2015
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Giuseppe Vitali Palma	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HFUI*ZA8M01Z	A	Z8GA	01/13/2015
Amount	UoM	Unit type	ST ECOPACK Grade	
1900.000	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	10.2X9.2X4.5	2	Through-hole	
Comment	Package: to 220 isol full pack 0.5 ab; MD valid for STPS30SM120SFP			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HFUI*ZA8M01Z					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other Inorganic Material	7.907	mg	Supplier	Silicon die	Silicon	7440-21-3		7.536	mg	953080	3966
Silicon Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.243	mg	30732	128
Silicon Die				supplier	metallization	Titanium (Ti)	7440-32-6		0.005	mg	632	3
Silicon Die				supplier	metallization	Tungsten (W)	7440-33-7		0.009	mg	1138	5
Silicon Die				supplier	metallization	Nickel (Ni)	7440-02-0		0.026	mg	3288	14
Silicon Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.036	mg	4553	19
Silicon Die				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	379	2
Silicon Die				supplier	back side metallization	Gold (Au)	7440-57-5		0.009	mg	1138	5
Silicon Die				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.04	mg	5059	21
Leadframe	Copper and its alloy	1013.537	mg	Supplier	Alloy	Copper(Cu)	7440-50-8		1011.506	mg	997996	532372
Leadframe				Supplier	Alloy	Iron(Fe)	7439-89-6		1.015	mg	1001	534
Leadframe				Supplier	Alloy	Lead(Pb)	7439-92-1		0.508	mg	501	267
Leadframe				Supplier	Alloy	Iron phosphide (Fe2P)	1310-43-6		0.508	mg	501	267
Die Attach	Other Organic Material	2.43	mg	Supplier	Soft Solder	Tin(Sn)	7440-31-5		0.049	mg	20165	26
Die Attach				Supplier	Soft Solder	Silver(Ag)	7440-22-4		0.061	mg	25103	32
Die Attach				JIG R	Soft Solder	Lead	7439-92-1	7a-Lead in high me	2.32	mg	954733	1221
Bonding wire	Other Inorganic Material	27.354	mg	Supplier	Bonding wire	Aluminum(Al)	84195-93-7		27.354	mg	1000000	14397
Encapsulation	Other Organic Material	819.452	mg	Supplier	Molding compound	Solid Epoxy Resin	Proprietary		81.982	mg	100045	43148
Encapsulation				Supplier	Molding compound	Phenol Resin	Proprietary		57.388	mg	70032	30204
Encapsulation				Supplier	Molding compound	Fused Silica	60676-86-0		41.401	mg	50523	21790
Encapsulation				Supplier	Molding compound	Crystalline Silica	14808-60-7		614.496	mg	749887	323419
Encapsulation				Supplier	Molding compound	Carbon Black	1333-86-4		0.41	mg	500	216
Encapsulation				Supplier	Molding compound	Metal Hydroxide	Proprietary		23.775	mg	29013	12513
Finishing	Other Inorganic Material	29.32	mg	Supplier	Connection Coating	Tin(Sn)	7440-31-5		29.32	mg	1000000	15432